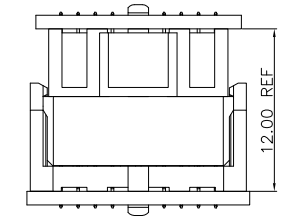
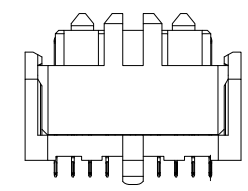
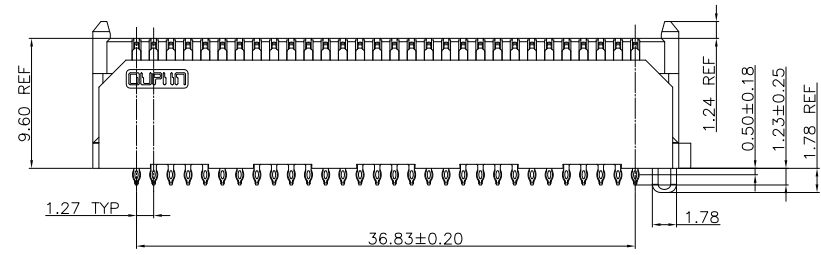
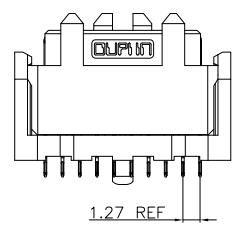
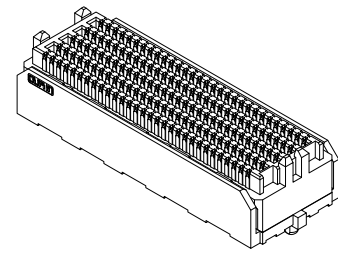
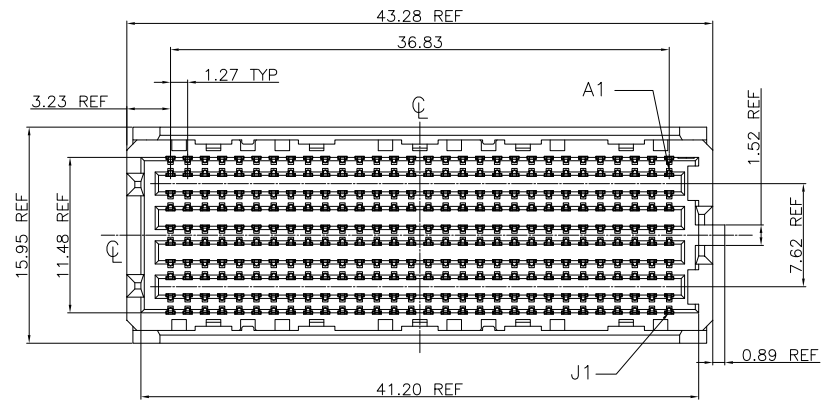


REV.	SPECIFICATION	ECN NO.	APPD.
R1		ECN220514	

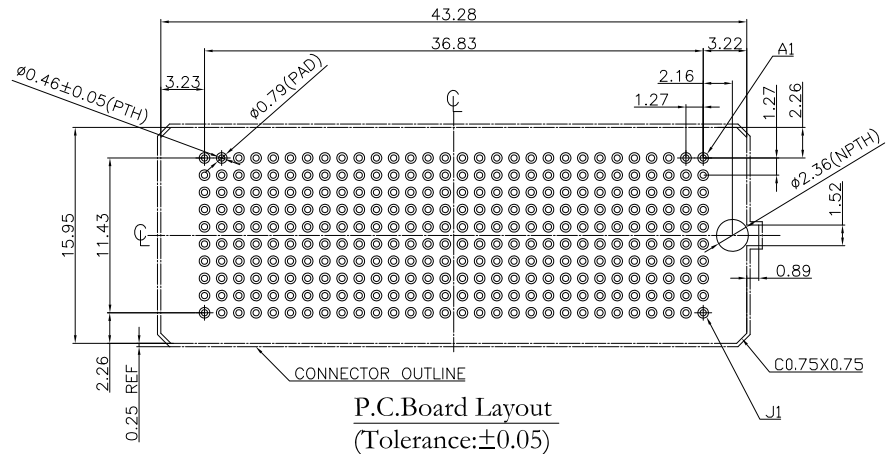
Material and Plating:
Housing: LCP, UL94V-0, Black.
Signal Contacts :Phosphor Bronze.
30u"Au+Pd/Ni on Contact Area and 80u" Min Tin Plated on Press Fit over nickel 50u" Min .

Electrical Characteristics:
Current Rating: Signal Pin: 2.7A.
Voltage Rating: 240V AC .
Dielectric Withstanding Voltage: 500V AC For 1 minute.
Insulator Resistance: 5000MΩ min at DC 500V.
Contact Resistance: Signal: 45mΩ max .
Operating Temperature: -55°C ~ +125°C .

***RoHS Compliant**



Mating Height



2322- 10 X 30 M B 7 P P 2 A

Series — 2322-
Row — 10
Position Per Row — X
M: Male
B: Dip Tin Plated
Contact Au+Pd/Ni Plated
7: 30μ"

P: Press Fit Type
T: Tape & Reel Package
U: Tube Package
A: Tray Package
2:Code 2 height 10.84mm
N: W/O Post
P: With Post

Tolerances	Dwg. No.	2322-D0000-007		Title:	
x = ±0.5	Projection	⊕ ⊖		2322 Series High Speed Board to Board Pitch 1.27mm	
.x = ±0.25	Unit	mm	Scale		1:1
.xx = ±0.15	Drawn By	WP 05/03'22			

OUPIN			
OUPIN ELECTRONIC(KUNSHAN) CO., LTD.			
P/N: 2322-10X30MB7PP2A			
SHEET	1/1	Ver. No.	R1